

Application S/N 10/626,242
Amendment dated: June 10, 2005
Response to Office Action dated: March 10, 2005

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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (canceled) A method of forming a multilayer circuit board having inverted microvias, comprising the steps of:

providing at least a first substrate core and a second substrate core each of said first substrate core and said second substrate core having a top conductive layer on at least a top side;

forming a microvia on a bottom side of at least one among the first substrate core and the second substrate core, wherein the microvia would reach to the top conductive layer on at least the top side of at least one among the first substrate core and the second substrate core;

applying a conductive layer to the microvia to interconnect a bottom conductive layer of at least one among the first substrate core and the second substrate core to the top conductive layer of at least one among the first substrate core and the second substrate core;

patterning at least one among the top conductive layer and the bottom conductive layer of at least one among the first substrate core and the second substrate core;

applying an adhesive / bonding layer between at least the first substrate core and the second substrate core;

forming a hole through the first substrate core, the adhesive / bonding layer and the second substrate core; and

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applying a conductive layer to the hole to interconnect at least two among the top conductive layer of the first substrate core, the top conductive layer of the second substrate core, the bottom conductive layer of the first substrate core, and the bottom conductive layer of the second substrate core.

2. (canceled) The method of claim 1, wherein the step of forming the microvia comprises forming the microvia on the bottom side of the first substrate core and forming a separate microvia on the bottom side of the second substrate core such that each microvia reaches the respective top conductive layer on the first substrate core and the second substrate core.

3. (canceled) The method of claim 1, wherein the step of patterning comprises patterning the top conductive layer and the bottom conductive layer of the first substrate core and patterning the top conductive layer and the bottom conductive layer of the second substrate core.

4. (canceled) The method of claim 1, wherein the step of applying the adhesive / bonding layer comprises applying a dielectric layer between the bottom layers of the first substrate core and the second substrate core.